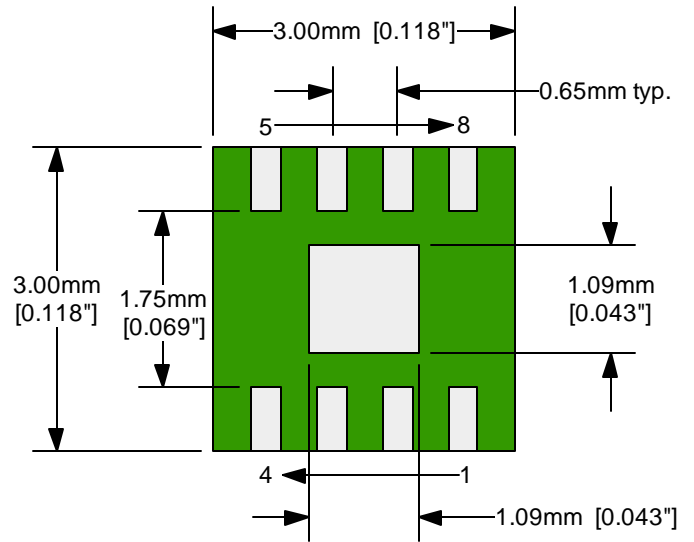
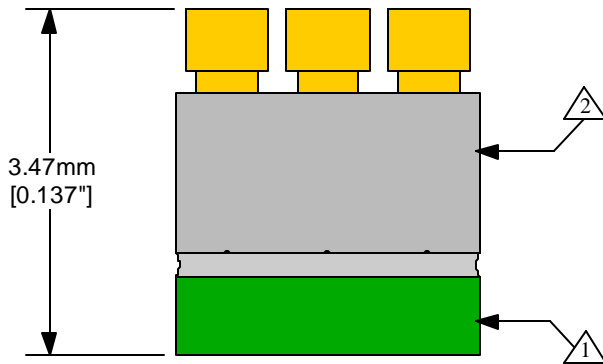


Top View



Bottom View



Side View


- △1 Substrate: 0.79mm ±0.18mm [0.031" ±0.007"]
FR4/G10 or equivalent high temp material. Non-clad.

- △2 Substrate: 1.59mm ±0.18mm [0.062" ±0.007"]
FR4/G10 or equivalent high temp material. Non-clad.

- △3 Pins: shell material- Brass Alloy 360 1/2 hard;
finish- 0.25µm [10µ"] Au over 1.27µm [50µ"] Ni
(min.). Contact material- BeCu; finish 0.25µm
[10µ"] Au over 2.54µm [100µ"] Ni (min.).

Description: 8 position MLF surface mount foot
8 position (+1 Gnd index pin). 1.0mm pitch UGA female receptacles (top) to 8 position, 0.65mm MLF pattern

Tolerances: diameters ±0.03mm [±0.001"], PCB perimeters ±0.13mm [±0.005"], PCB thicknesses ±0.18mm [±0.007"], pitches (from true position) ±0.08mm [±0.003"], all other tolerances ±0.13mm [±0.005"] unless stated otherwise. Materials and specifications are subject to change without notice.

	SF-MLF8C-A-02 Drawing	Status: Released	Scale: 12:1	Rev: A
	© 2004 IRONWOOD ELECTRONICS, INC. PO BOX 21151 ST. PAUL, MN 55121 Tele: (651) 452-8100 www.ironwoodelectronics.com	Drawing: H. Hansen		Date: 11/29/04
		File: SF-MLF8C-A-02 Dwg	Modified:	